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(54) Title: ENCAPSULANT FILM AND PHOTOVOLTAIC MODULE COMPRISING THE SAME

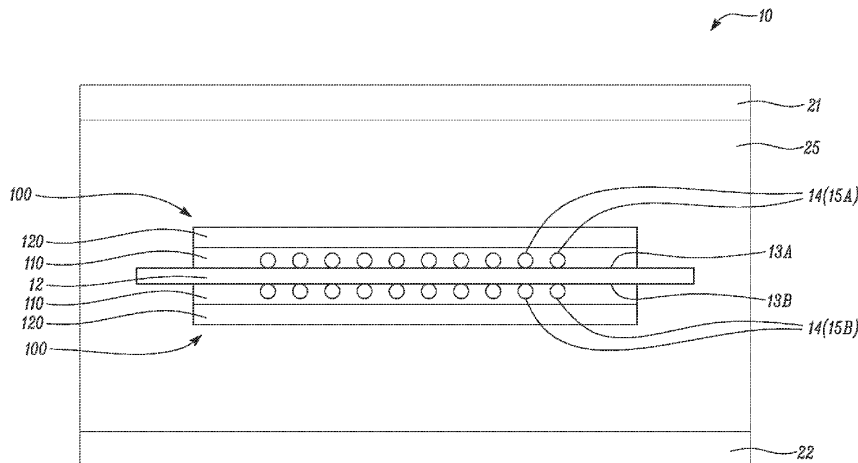


FIG. 1

(57) Abstract: An encapsulant film for a photovoltaic module includes an encapsulating layer and a heat resistant layer disposed adjacent to the encapsulating layer. The encapsulating layer includes polyethylene in an amount of 50% to 100%, by weight. The heat resistant layer includes one of ethylene vinyl alcohol (EVOH), polymethyl methacrylate (PMMA), polymethyl pentene (PMP), cycloolefin polymer (COP), cycloolefin copolymer (COC), polylactic acid (PLA), polyethylene furanoate (PEF), isosorbide polymer, and polycarbonate (PC) in an amount of 50% to 100%, by weight.

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